

RoHS Compliant Product  
A suffix of "-C" specifies halogen free

## DESCRIPTION

SSD55P30J uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

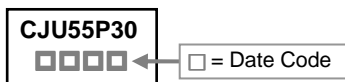
## FEATURES

- High density cell design for ultra low  $R_{DS(ON)}$
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high  $E_{AS}$
- Excellent package for good heat dissipation

## APPLICATIONS

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible Power Supply(UPS)

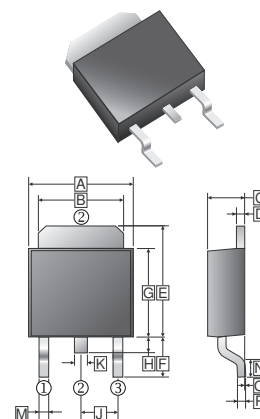
## MARKING



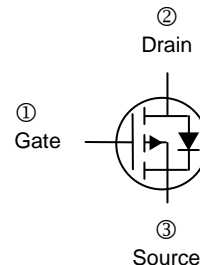
## PACKAGE INFORMATION

Package	MPQ	Leader Size
TO-252	2.5K	13 inch

## TO-252(D-Pack)



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	6.35	6.90	J	2.186	2.386
B	4.95	5.50	K	0.64	1.14
C	2.10	2.50	M	0.50	1.14
D	0.43	0.9	N	1.3	1.8
E	6.0	7.5	O	0	0.13
F	2.90	REF.	P	0.58	REF.
G	5.40	6.40			
H	0.60	1.20			



## ABSOLUTE MAXIMUM RATINGS ( $T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-55	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	-30	A
Pulsed Drain Current	$I_{DM}$	-120	A
Single Pulsed Avalanche Energy <sup>1</sup>	$E_{AS}$	225	mJ
Power Dissipation	$P_D$	1.25	W
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	100	$^{\circ}\text{C}/\text{W}$
Lead Temperature for Soldering Purposes @ 1/8" from case for 10s	$T_L$	260	$^{\circ}\text{C}$
Junction and Storage Temperature Range	$T_J, T_{STG}$	150, -55~150	$^{\circ}\text{C}$

Notes :

1. Test condition:  $V_{DD} = -25\text{V}$ ,  $L = 0.5\text{mH}$ ,  $R_G = 25\Omega$ , Starting  $T_J = 25^{\circ}\text{C}$ .

**ELECTRICAL CHARACTERISTICS** ( $T_A=25^\circ C$  unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Condition
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	-55	-	-	V	$V_{GS}=0, I_D = -250\mu A$
Zero Gate Voltage Drain Current	$I_{DSS}$	-	-	-1	$\mu A$	$V_{DS} = -55V, V_{GS}=0$
Gate-Body Leakage Current	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{DS}=0V, V_{GS}= \pm 20V$
<b>On Characteristics <sup>1</sup></b>						
Gate-Threshold Voltage	$V_{GS(th)}$	-2	-	-4	V	$V_{DS}=V_{GS}, I_D = -250\mu A$
Static Drain-Source On-Resistance	$R_{DS(ON)}$	-	-	40	m $\Omega$	$V_{GS} = -10V, I_D = -15A$
Forward Transconductance	$g_{fs}$	8	-	-	S	$V_{DS} = -25V, I_D = -16A$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	-	3500	-	pF	$V_{DS} = -30V$ $V_{GS}=0$ $f=1MHz$
Output Capacitance	$C_{oss}$	-	240	-		
Reverse Transfer Capacitance	$C_{rss}$	-	153	-		
<b>Switching Characteristics</b>						
Total Gate Charge	$Q_g$	-	56	-	nC	$V_{DS} = -30V$ $V_{GS} = -10V$ $I_D = -15A$
Gate-Source Charge	$Q_{gs}$	-	11	-		
Gate-Drain Charge	$Q_{gd}$	-	24	-		
Turn-on Delay Time	$T_{d(on)}$	-	12	-	nS	$V_{DD} = -30V$ $V_{GS} = -10V$ $R_G=3\Omega$ $I_D = -15A$
Rise Time	$T_r$	-	15	-		
Turn-off Delay Time	$T_{d(off)}$	-	38	-		
Fall Time	$T_f$	-	15	-		
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>1</sup>	$V_{SD}$	-	-	-1.2	V	$V_{GS}=0, I_S = -24A$
Continuous Drain-Source Diode Forward Current	$I_S$	-	-	-30	A	
Pulsed Drain-Source Diode Forward Current	$I_{SM}$	-	-	-120	A	

Notes:

1. Pulse test : Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .

**CHARACTERISTIC CURVE**

